We sell solely to business customers and public institutions, all prices plus VAT and delivery costs.



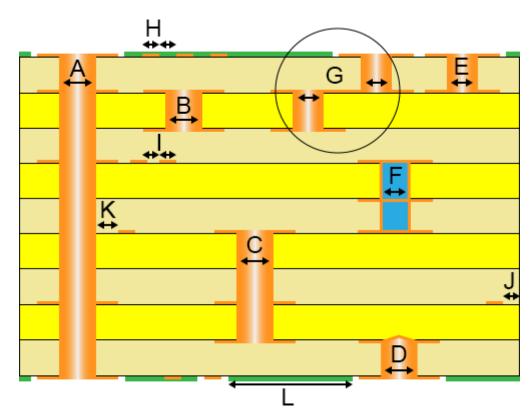
1 - 48 Layers1WD Express30 Years experienceDISPATCH & SUPPORTfrom Germany, shipping costs (e.g. 1kg)

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Design Parameters



Here you can download the Basic Design Rules incl. Design Parameters.

The following parameters are exemplary for 35µm copper thickness.

For other thicknesses / special production, please contact our technical hotline: +49 (0)8104 628 210.

A, B, C	Via, buried via	aspect ratio	1:10	1:12
		diameter	200µm	150µm
		via pad	400μm	330µm
		annular ring	100µm circular	90µm circular
	Component hole:			
	Annular ring circular + 25µm			
D	Blind Via, mechanical	aspect ratio	1:1	1:1.2
i	max. Ø 300µm	diameter	200µm	150µm
i		via pad	400µm	350µm
		annular ring	100µm circular	100µm circular
E	Blind Via, laser	aspect ratio	-	1:1
		diameter	-	100µm
		via pad	-	280µm
		annular ring		90µm circular*
F	Stacked Vias	aspect ratio	-	-
	Disproportional high effort. Please contact our CAM	diameter	-	-
	department for alternatives.	via pad	-	-
		annular ring		
G	Staggered Vias	aspect ratio	1:1 - 1:12 **	1:1 - 1:12 **
		diameter	200µm	100µm
		via pad	400µm	300µm
		annular ring	100µm circular	90µm circular
H, I	Conductors	width	100µm	75µm 90µm
	(see Conductor/copper thickness)	space	100µm	100µm 90µm
	•			

Standard (min.)

Special production(min.)

Index			Standard (min.)	Special production(min.)		
	Conductor/pad to milling edge Conductor/pad to scoring edge	'	•	200µm 500µm		
K	Conductor/pad to hole (PTH, NPTH)	space	200μm	200μm		
L	1,3	clearance bridge	·	25μm circ. (BGA) 80μm		
	1,	clearance bridge		50µm circular 125µm		

^{*} Prior data check necessary. ** see Buried Via, Blind Via

Additional information

- Basic Design Rules download
- Overview of technical options
- Conductor / Copper thickness
- Conductor / Ampacity
- Marking print

